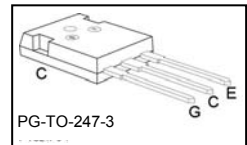
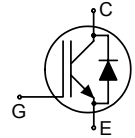


Low Loss DuoPack : IGBT in TrenchStop® and Fieldstop technology  
with soft, fast recovery anti-parallel EmCon HE diode

- Very low  $V_{CE(sat)}$  1.5 V (typ.)
- Maximum Junction Temperature 175 °C
- Short circuit withstand time – 5µs
- Positive temperature coefficient in  $V_{CE(sat)}$
- very tight parameter distribution
- high ruggedness, temperature stable behaviour
- very high switching speed
- Low EMI
- Very soft, fast recovery anti-parallel EmCon HE diode
- Qualified according to JEDEC<sup>1)</sup> for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models : <http://www.infineon.com/igbt/>



### Applications:

- Frequency Converters
- Uninterrupted Power Supply

Type	$V_{CE}$	$I_C$	$V_{CE(sat), T_j=25^\circ C}$	$T_{j,max}$	Marking	Package
IKW75N60T	600V	75A	1.5V	175°C	K75T60	PG-TO-247-3

### Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CE}$	600	V
DC collector current, limited by $T_{j,max}$	$I_C$	80 <sup>2)</sup>	A
$T_C = 25^\circ C$		75	
$T_C = 100^\circ C$			
Pulsed collector current, $t_p$ limited by $T_{j,max}$	$I_{C,puls}$	225	
Turn off safe operating area ( $V_{CE} \leq 600V, T_j \leq 175^\circ C$ )	-	225	
Diode forward current, limited by $T_{j,max}$	$I_F$	80 <sup>2)</sup>	
$T_C = 25^\circ C$		75	
$T_C = 100^\circ C$			
Diode pulsed current, $t_p$ limited by $T_{j,max}$	$I_{F,puls}$	225	
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Short circuit withstand time <sup>3)</sup>	$t_{SC}$	5	µs
$V_{GE} = 15V, V_{CC} \leq 400V, T_j \leq 150^\circ C$			
Power dissipation $T_C = 25^\circ C$	$P_{tot}$	428	W
Operating junction temperature	$T_j$	-40...+175	°C
Storage temperature	$T_{stg}$	-55...+175	
Soldering temperature, 1.6mm (0.063 in.) from case for 10s	-	260	

<sup>1)</sup> J-STD-020 and JESD-022

<sup>2)</sup> Value limited by bondwire

<sup>3)</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.

**Thermal Resistance**

Parameter	Symbol	Conditions	Max. Value	Unit
<b>Characteristic</b>				
IGBT thermal resistance, junction – case	$R_{thJC}$		0.35	K/W
Diode thermal resistance, junction – case	$R_{thJCD}$		0.6	
Thermal resistance, junction – ambient	$R_{thJA}$		40	

**Electrical Characteristic, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
<b>Static Characteristic</b>						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=0.2mA$	600	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C=75A$ $T_j=25^\circ\text{C}$ $T_j=175^\circ\text{C}$	- -	1.5 1.9	2.0 -	
Diode forward voltage	$V_F$	$V_{GE}=0V, I_F=75A$ $T_j=25^\circ\text{C}$ $T_j=175^\circ\text{C}$	- -	1.65 1.6	2.0 -	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=1.2mA, V_{CE}=V_{GE}$	4.1	4.9	5.7	
Zero gate voltage collector current	$I_{CES}$	$V_{CE}=600V,$ $V_{GE}=0V$ $T_j=25^\circ\text{C}$ $T_j=175^\circ\text{C}$	- -	- -	40 1000	$\mu\text{A}$
Gate-emitter leakage current	$I_{GES}$	$V_{CE}=0V, V_{GE}=20V$	-	-	100	nA
Transconductance	$g_{fs}$	$V_{CE}=20V, I_C=75A$	-	41	-	S
Integrated gate resistor	$R_{Gint}$			-		$\Omega$

**Dynamic Characteristic**

Input capacitance	$C_{iss}$	$V_{CE}=25V,$ $V_{GE}=0V,$ $f=1MHz$	-	4620	-	pF
Output capacitance	$C_{oss}$		-	288	-	
Reverse transfer capacitance	$C_{riss}$		-	137	-	
Gate charge	$Q_{Gate}$	$V_{CC}=480V, I_C=75A$ $V_{GE}=15V$	-	470	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	$L_E$		-	13	-	nH
Short circuit collector current <sup>1)</sup>	$I_{C(SC)}$	$V_{GE}=15V, t_{SC}\leq 5\mu s$ $V_{CC} = 400V,$ $T_j \leq 150^\circ\text{C}$	-	690	-	A

<sup>1)</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.

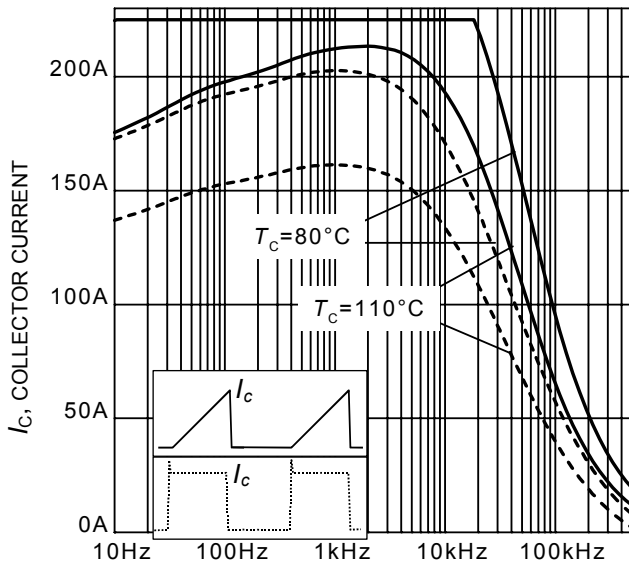
**Switching Characteristic, Inductive Load, at  $T_j=25^\circ\text{C}$** 

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>IGBT Characteristic</b>						
Turn-on delay time	$t_{d(on)}$	$T_j=25^\circ\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=75\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=5\Omega$ , $L_{\sigma}^{(1)}=100\text{nH}$ , $C_{\sigma}^{(1)}=39\text{pF}$ Energy losses include "tail" and diode reverse recovery.	-	33	-	ns
Rise time	$t_r$		-	36	-	
Turn-off delay time	$t_{d(off)}$		-	330	-	
Fall time	$t_f$		-	35	-	
Turn-on energy	$E_{on}$		-	2.0	-	mJ
Turn-off energy	$E_{off}$		-	2.5	-	
Total switching energy	$E_{ts}$		-	4.5	-	
<b>Anti-Parallel Diode Characteristic</b>						
Diode reverse recovery time	$t_{rr}$	$T_j=25^\circ\text{C}$ , $V_R=400\text{V}$ , $I_F=75\text{A}$ , $di_F/dt=1460\text{A}/\mu\text{s}$	-	121	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	2.4	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	38.5	-	A
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	921	-	$\text{A}/\mu\text{s}$

**Switching Characteristic, Inductive Load, at  $T_j=175^\circ\text{C}$** 

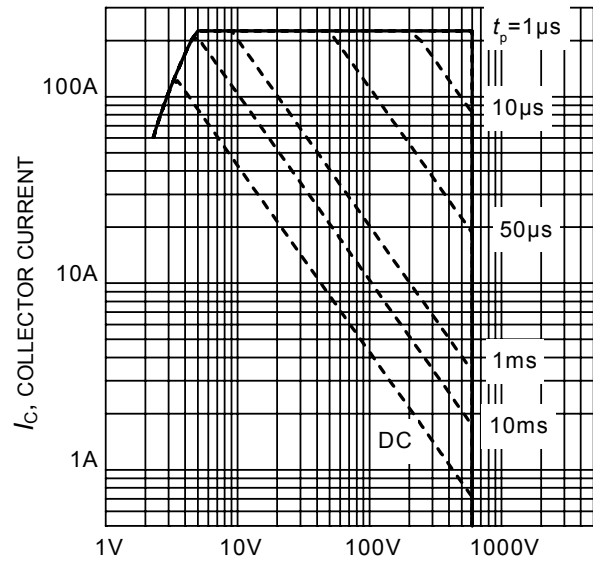
Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>IGBT Characteristic</b>						
Turn-on delay time	$t_{d(on)}$	$T_j=175^\circ\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=75\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=5\Omega$ $L_{\sigma}^{(1)}=100\text{nH}$ , $C_{\sigma}^{(1)}=39\text{pF}$ Energy losses include "tail" and diode reverse recovery.	-	32	-	ns
Rise time	$t_r$		-	37	-	
Turn-off delay time	$t_{d(off)}$		-	363	-	
Fall time	$t_f$		-	38	-	
Turn-on energy	$E_{on}$		-	2.9	-	mJ
Turn-off energy	$E_{off}$		-	2.9	-	
Total switching energy	$E_{ts}$		-	5.8	-	
<b>Anti-Parallel Diode Characteristic</b>						
Diode reverse recovery time	$t_{rr}$	$T_j=175^\circ\text{C}$ $V_R=400\text{V}$ , $I_F=75\text{A}$ , $di_F/dt=1460\text{A}/\mu\text{s}$	-	182	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	5.8	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	56.2	-	A
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	1013	-	$\text{A}/\mu\text{s}$

<sup>1)</sup> Leakage inductance  $L_{\sigma}$  and Stray capacity  $C_{\sigma}$  due to dynamic test circuit in Figure E.



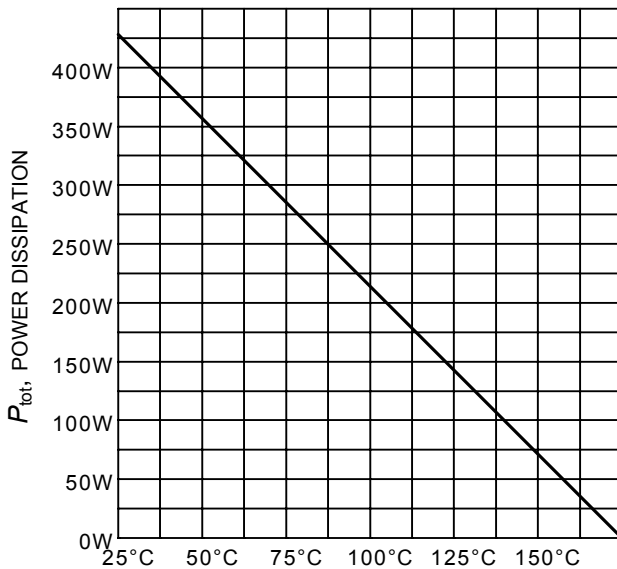
$f$ , SWITCHING FREQUENCY

**Figure 1. Collector current as a function of switching frequency**  
 ( $T_j \leq 175^\circ\text{C}$ ,  $D = 0.5$ ,  $V_{CE} = 400\text{V}$ ,  
 $V_{GE} = 0/+15\text{V}$ ,  $R_G = 5\Omega$ )



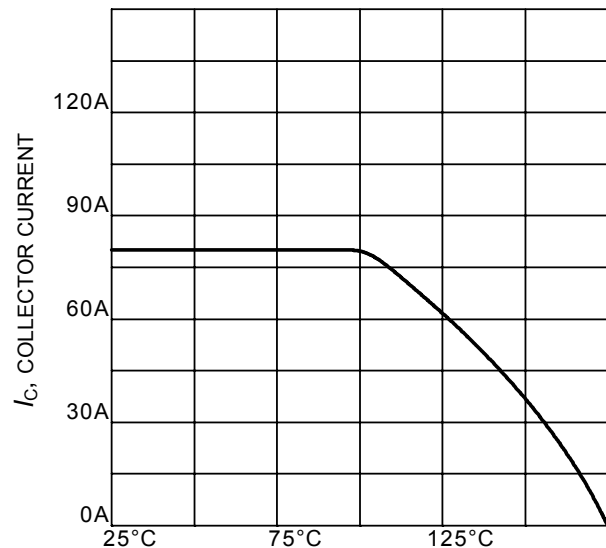
$V_{CE}$ , COLLECTOR-EMITTER VOLTAGE

**Figure 2. Safe operating area**  
 ( $D = 0$ ,  $T_C = 25^\circ\text{C}$ ,  $T_j \leq 175^\circ\text{C}$ ;  
 $V_{GE} = 15\text{V}$ )



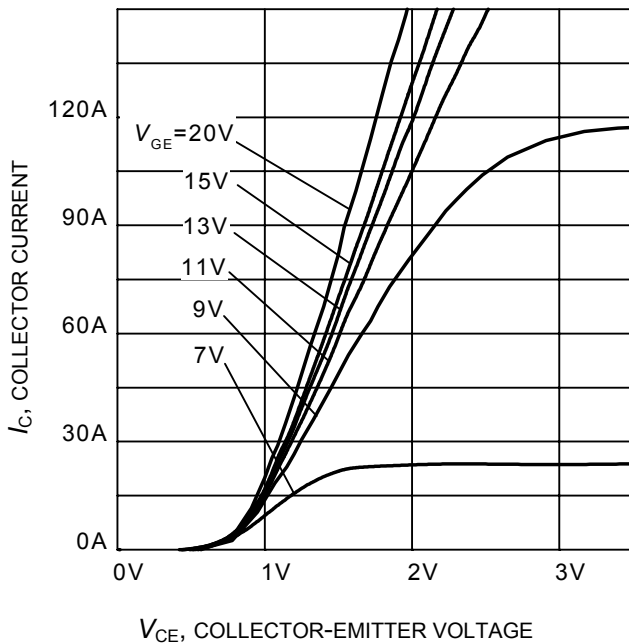
$T_C$ , CASE TEMPERATURE

**Figure 3. Power dissipation as a function of case temperature**  
 ( $T_j \leq 175^\circ\text{C}$ )

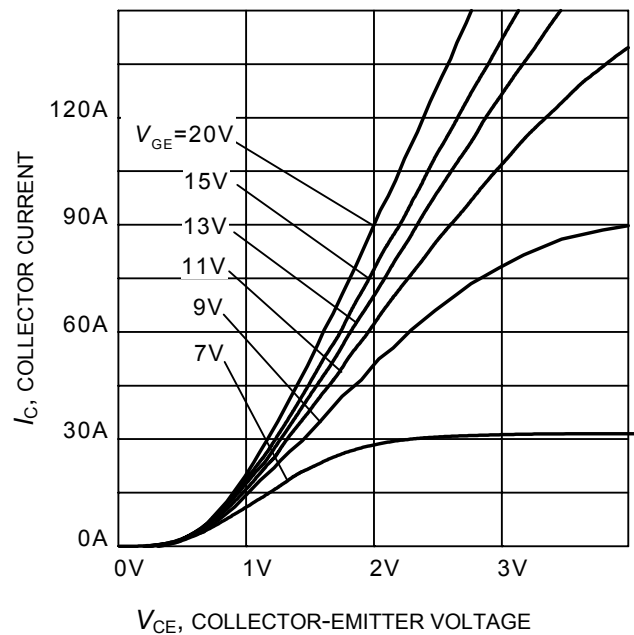


$T_C$ , CASE TEMPERATURE

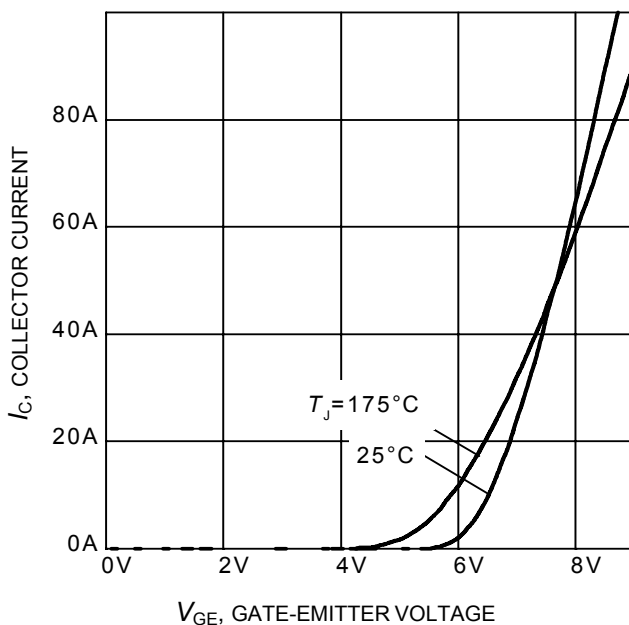
**Figure 4. DC Collector current as a function of case temperature**  
 ( $V_{GE} \geq 15\text{V}$ ,  $T_j \leq 175^\circ\text{C}$ )



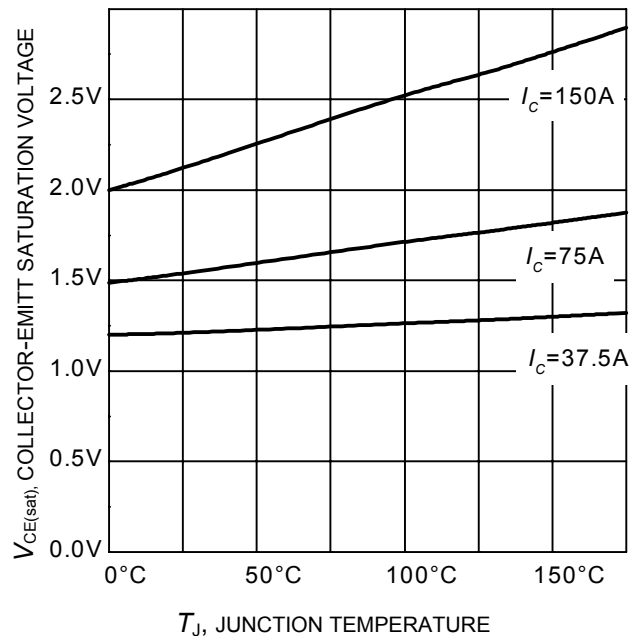
**Figure 5. Typical output characteristic**  
( $T_j = 25^\circ\text{C}$ )



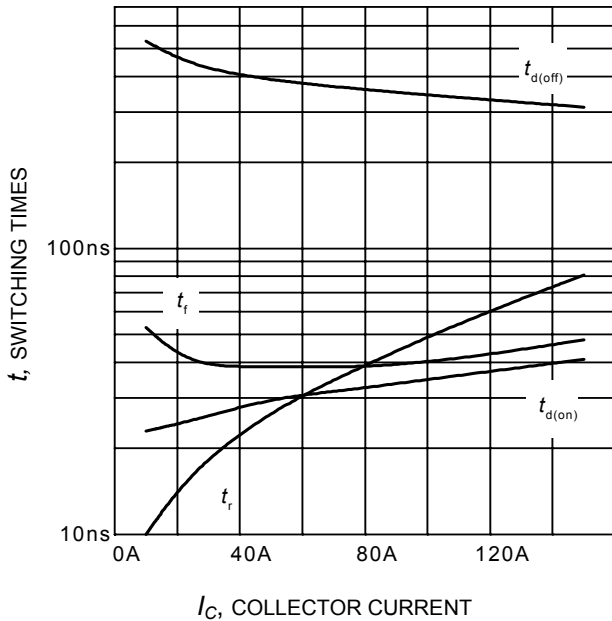
**Figure 6. Typical output characteristic**  
( $T_j = 175^\circ\text{C}$ )



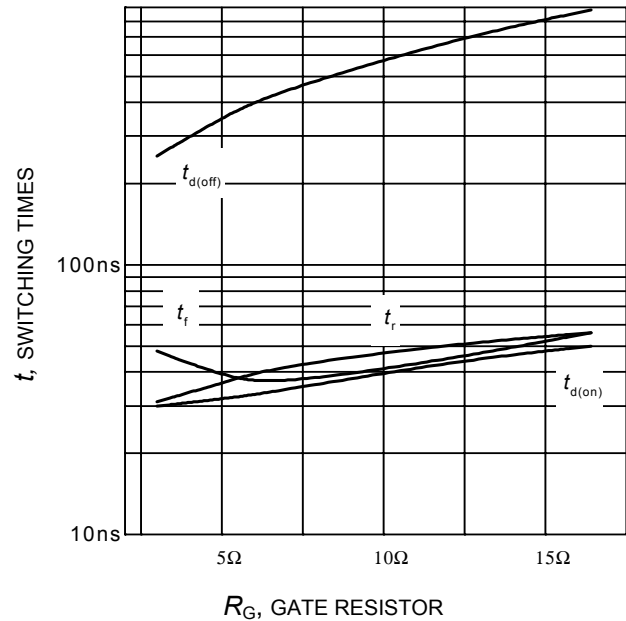
**Figure 7. Typical transfer characteristic**  
( $V_{CE} = 20\text{V}$ )



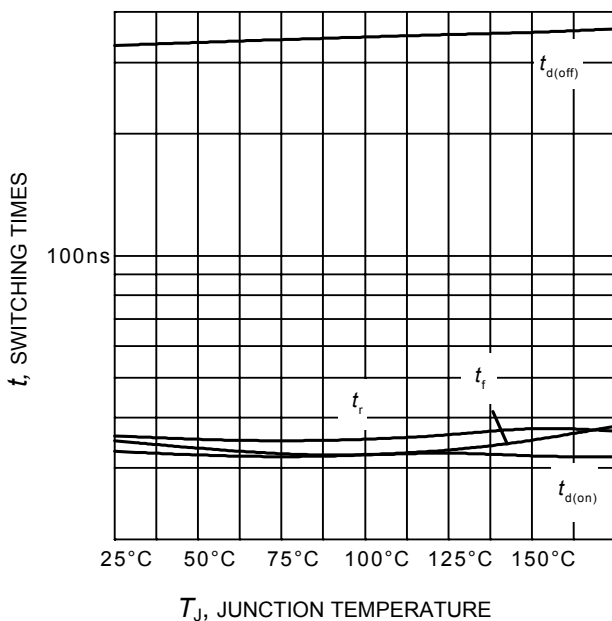
**Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature**  
( $V_{GE} = 15\text{V}$ )



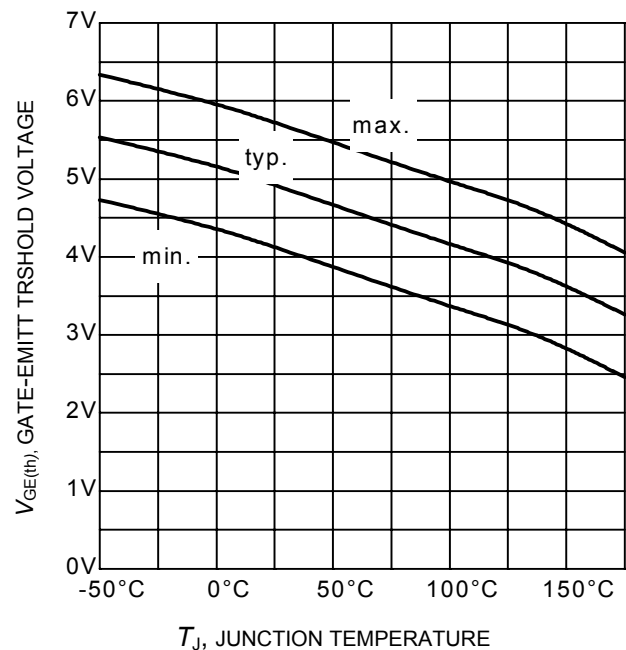
**Figure 9. Typical switching times as a function of collector current**  
 (inductive load,  $T_J=175^\circ\text{C}$ ,  
 $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $R_G = 5\Omega$ ,  
 Dynamic test circuit in Figure E)



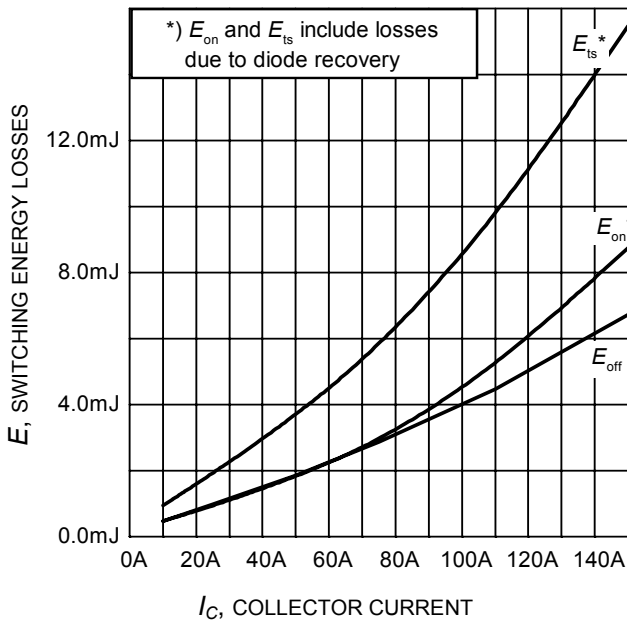
**Figure 10. Typical switching times as a function of gate resistor**  
 (inductive load,  $T_J = 175^\circ\text{C}$ ,  
 $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 75\text{A}$ ,  
 Dynamic test circuit in Figure E)



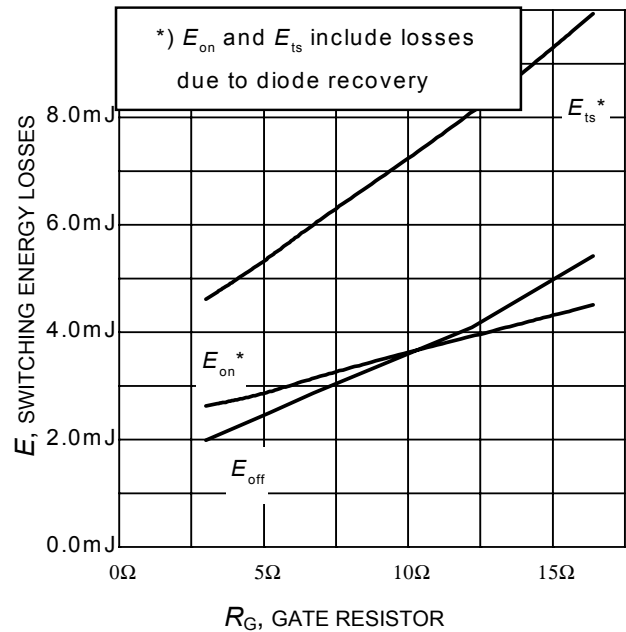
**Figure 11. Typical switching times as a function of junction temperature**  
 (inductive load,  $V_{CE} = 400\text{V}$ ,  
 $V_{GE} = 0/15\text{V}$ ,  $I_C = 10\text{A}$ ,  $R_G=5\Omega$ ,  
 Dynamic test circuit in Figure E)



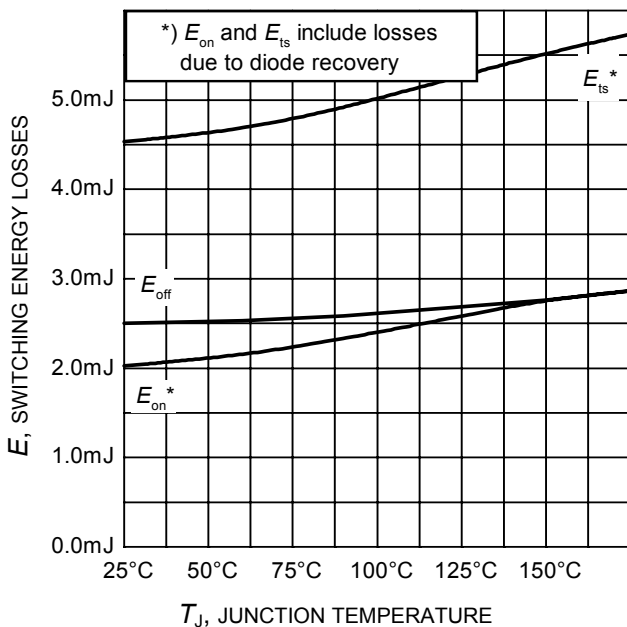
**Figure 12. Gate-emitter threshold voltage as a function of junction temperature**  
 ( $I_C = 1.2\text{mA}$ )



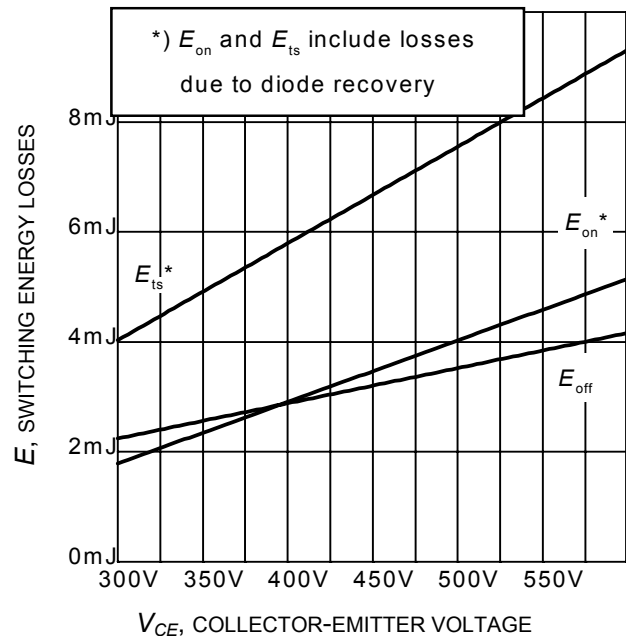
**Figure 13. Typical switching energy losses as a function of collector current**  
 (inductive load,  $T_J = 175^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $R_G = 5\Omega$ , Dynamic test circuit in Figure E)



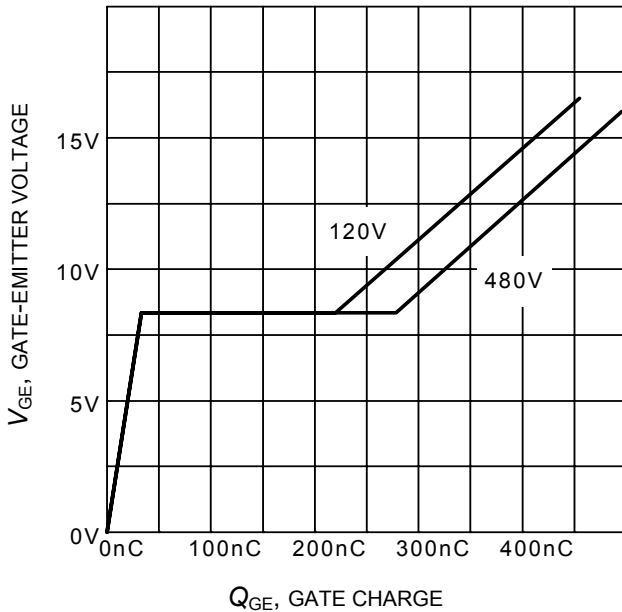
**Figure 14. Typical switching energy losses as a function of gate resistor**  
 (inductive load,  $T_J = 175^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 75\text{A}$ , Dynamic test circuit in Figure E)



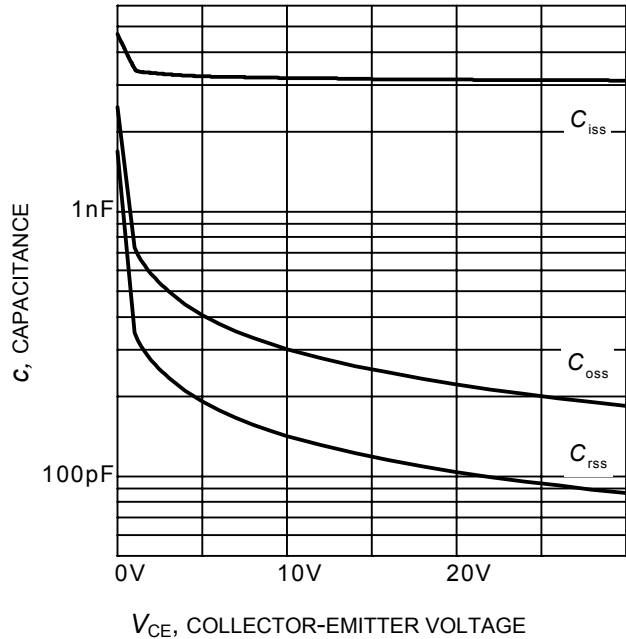
**Figure 15. Typical switching energy losses as a function of junction temperature**  
 (inductive load,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 75\text{A}$ ,  $R_G = 5\Omega$ , Dynamic test circuit in Figure E)



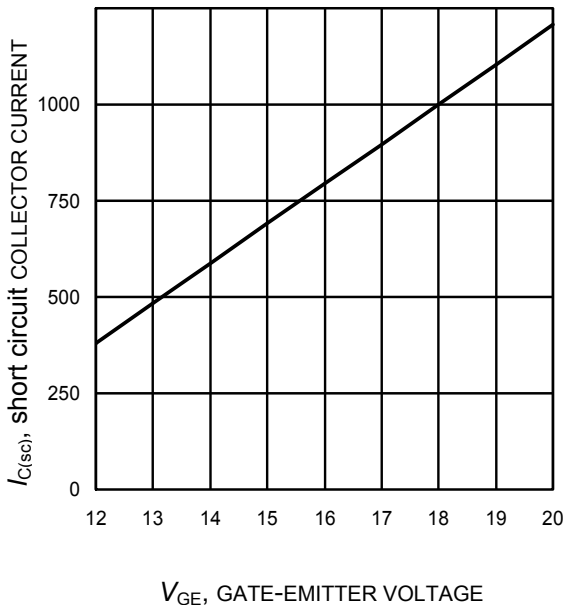
**Figure 16. Typical switching energy losses as a function of collector emitter voltage**  
 (inductive load,  $T_J = 175^\circ\text{C}$ ,  $V_{GE} = 0/15\text{V}$ ,  $I_C = 75\text{A}$ ,  $R_G = 5\Omega$ , Dynamic test circuit in Figure E)



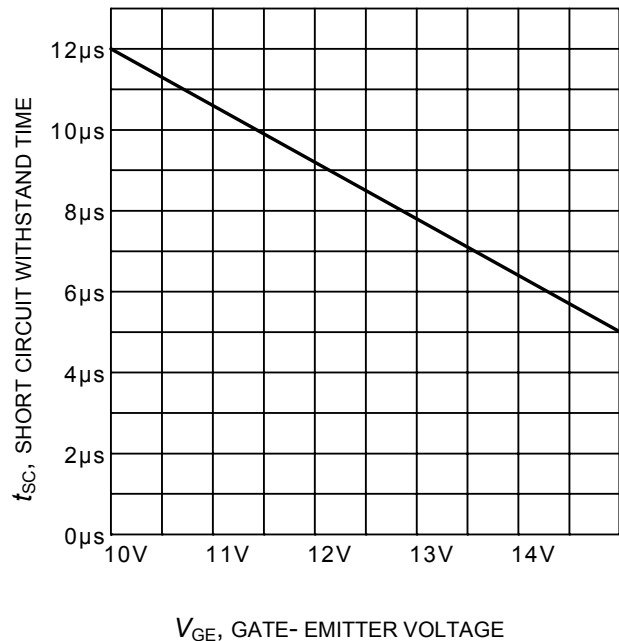
**Figure 17. Typical gate charge**  
( $I_C=75\text{ A}$ )



**Figure 18. Typical capacitance as a function of collector-emitter voltage**  
( $V_{GE}=0\text{V}$ ,  $f = 1\text{ MHz}$ )

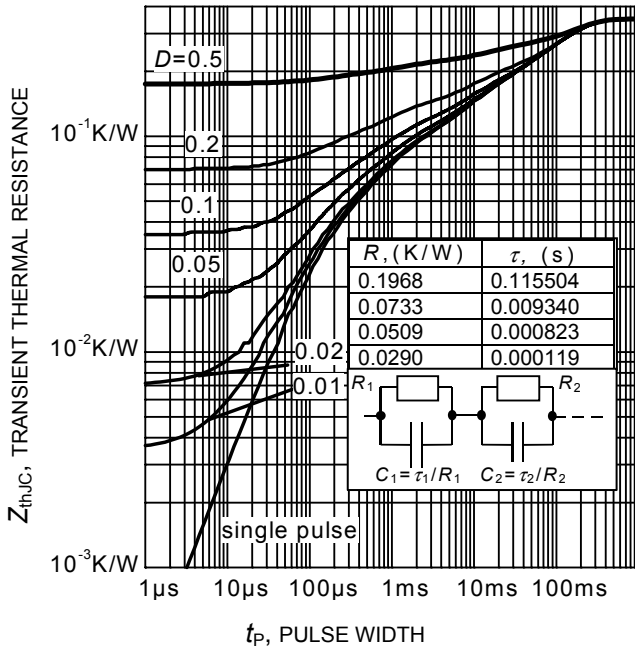


**Figure 19. Typical short circuit collector current as a function of gate-emitter voltage**  
( $V_{CE} \leq 400\text{V}$ ,  $T_J \leq 150^\circ\text{C}$ )

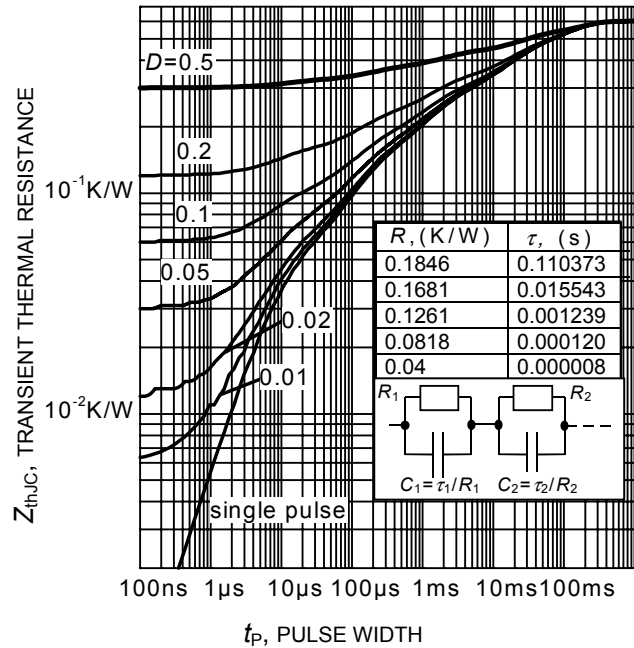


**Figure 20. Short circuit withstand time as a function of gate-emitter voltage**  
( $V_{CE}=400\text{V}$ , start at  $T_J=25^\circ\text{C}$ ,  $T_{Jmax}<150^\circ\text{C}$ )

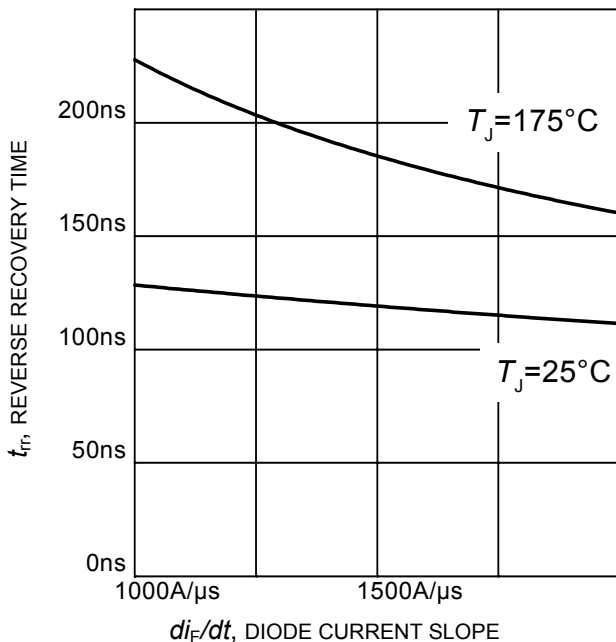




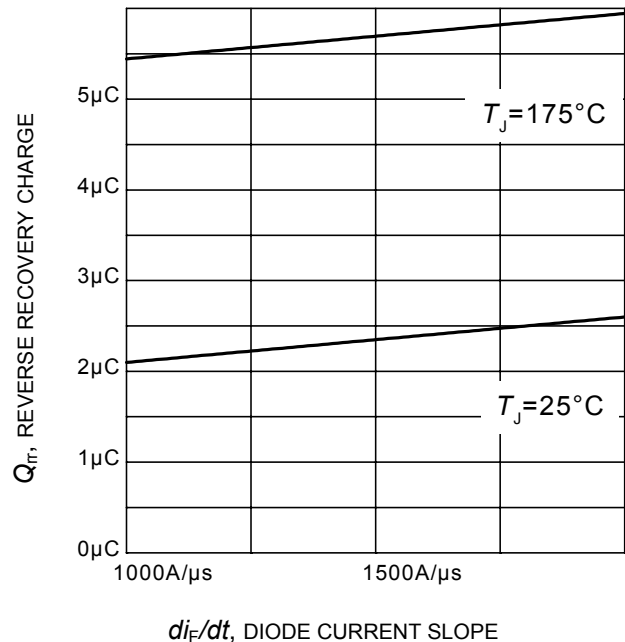
**Figure 21. IGBT transient thermal resistance**  
( $D = t_p / T$ )



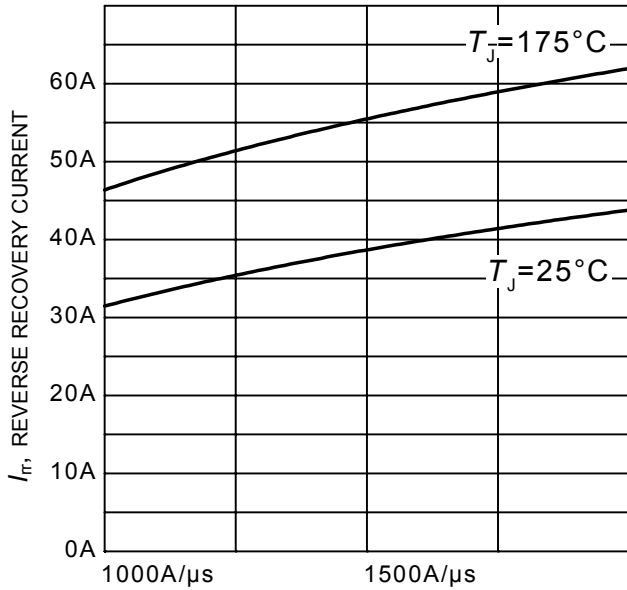
**Figure 22. Diode transient thermal impedance as a function of pulse width**  
( $D = t_p / T$ )



**Figure 23. Typical reverse recovery time as a function of diode current slope**  
( $V_R = 400V$ ,  $I_F = 75A$ ,  
Dynamic test circuit in Figure E)



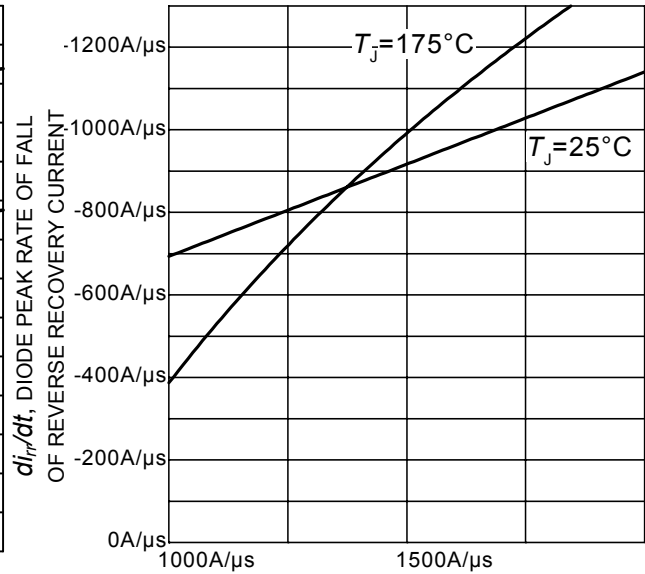
**Figure 24. Typical reverse recovery charge as a function of diode current slope**  
( $V_R = 400V$ ,  $I_F = 75A$ ,  
Dynamic test circuit in Figure E)



$di_F/dt$ , DIODE CURRENT SLOPE

**Figure 25. Typical reverse recovery current as a function of diode current slope**

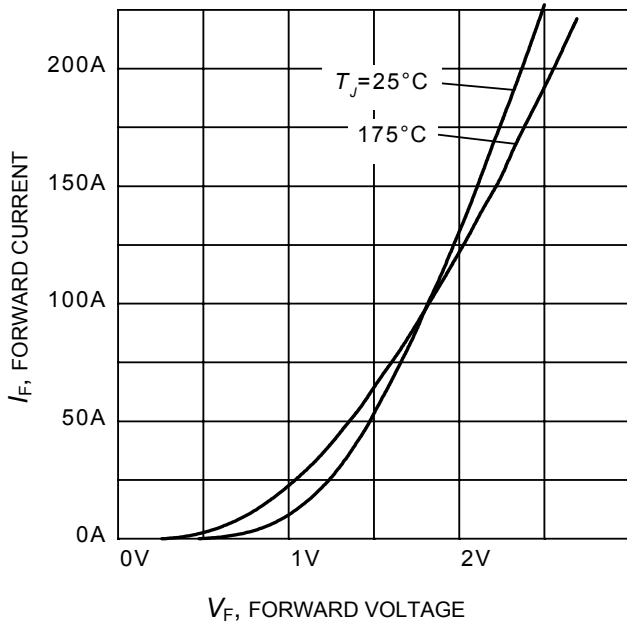
( $V_R = 400V$ ,  $I_F = 75A$ ,  
Dynamic test circuit in Figure E)



$di_F/dt$ , DIODE CURRENT SLOPE

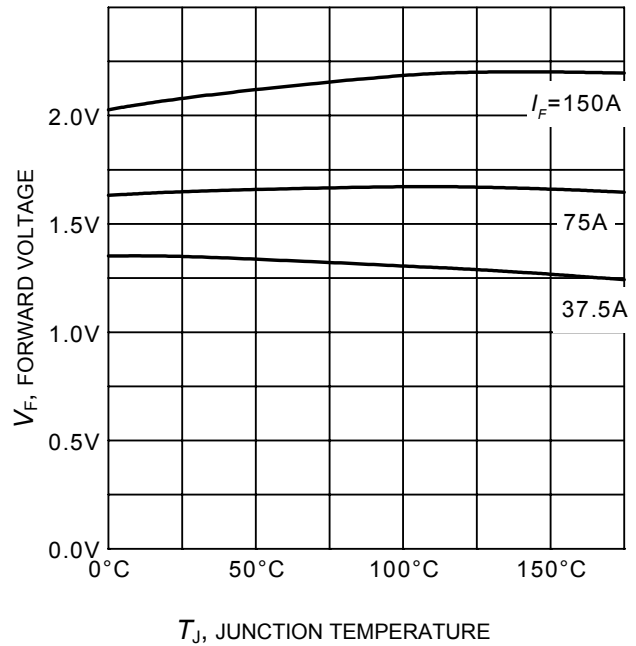
**Figure 26. Typical diode peak rate of fall of reverse recovery current as a function of diode current slope**

( $V_R = 400V$ ,  $I_F = 75A$ ,  
Dynamic test circuit in Figure E)



$V_F$ , FORWARD VOLTAGE

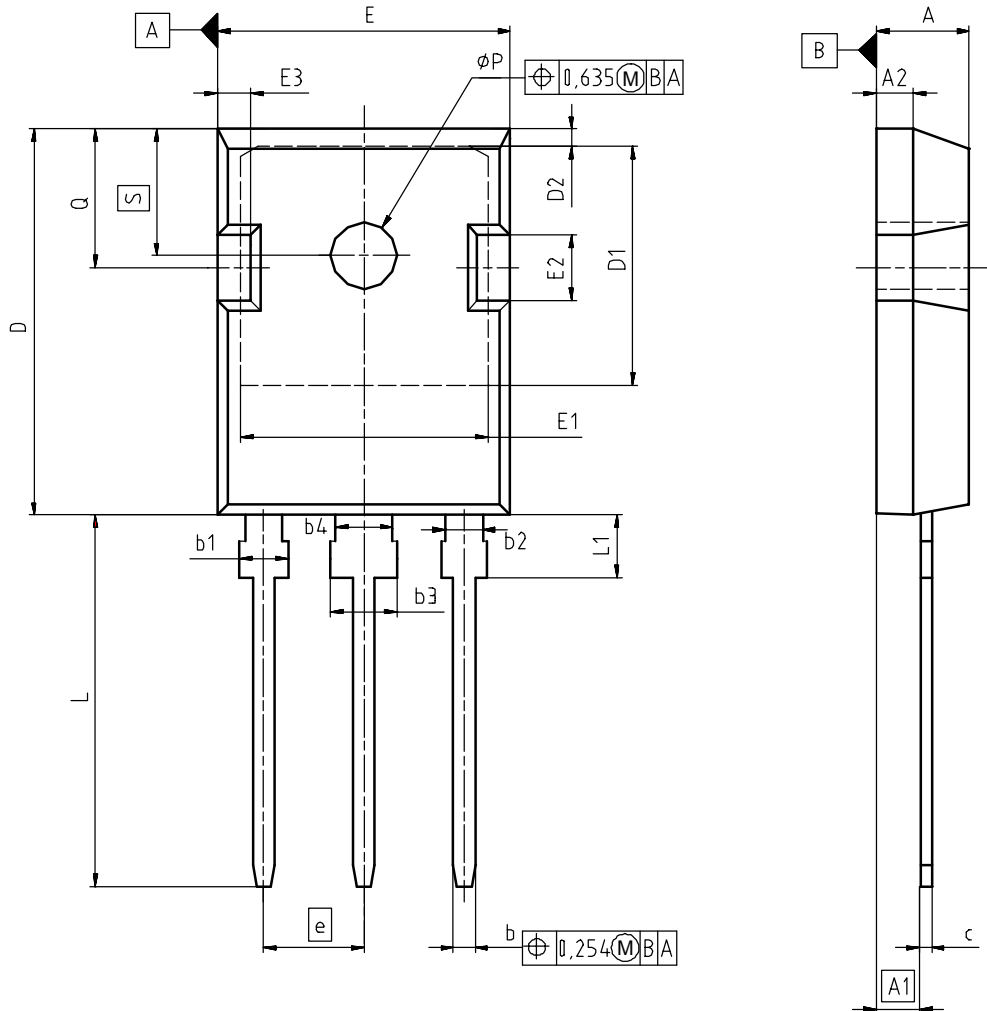
**Figure 27. Typical diode forward current as a function of forward voltage**



$T_J$ , JUNCTION TEMPERATURE

**Figure 28. Typical diode forward voltage as a function of junction temperature**

### PG-TO247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.16	0.193	0.203
A1	2.27	2.53	0.089	0.099
A2	1.85	2.11	0.073	0.083
b	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
c	0.55	0.68	0.022	0.027
D	20.82	21.10	0.820	0.831
D1	16.25	17.65	0.640	0.695
D2	1.05	1.35	0.041	0.053
E	15.70	16.03	0.618	0.631
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.68	2.60	0.066	0.102
e	5.44		0.214	
N	3		3	
L	19.80	20.31	0.780	0.799
L1	4.17	4.47	0.164	0.176
$\phi P$	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248

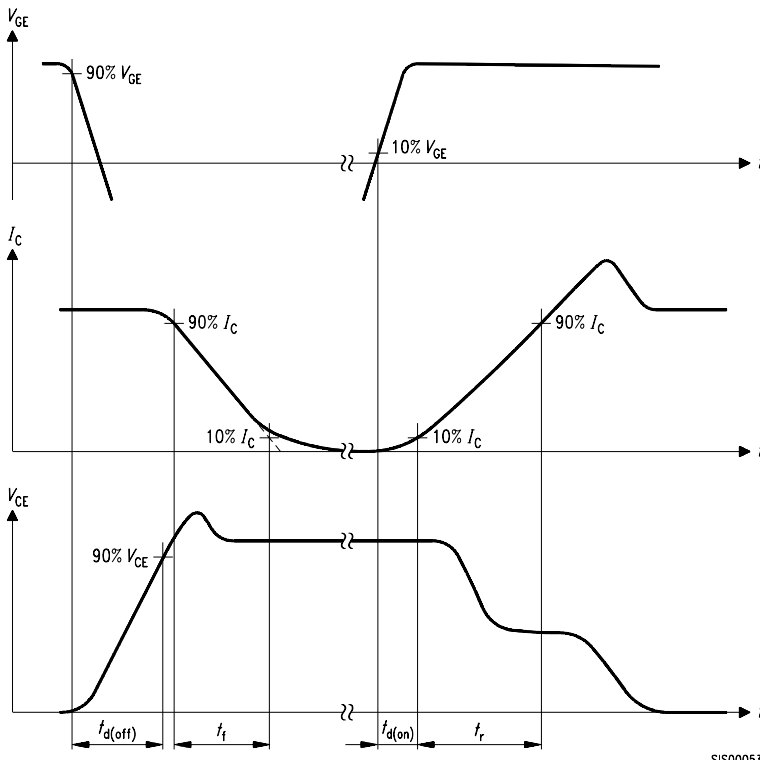
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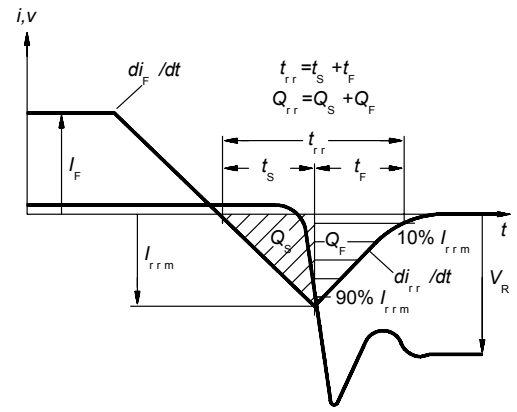
EUROPEAN PROJECTION

ISSUE DATE  
17-12-2007

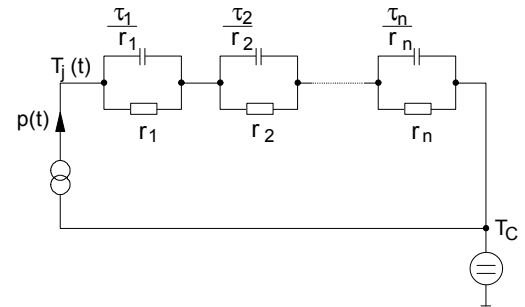
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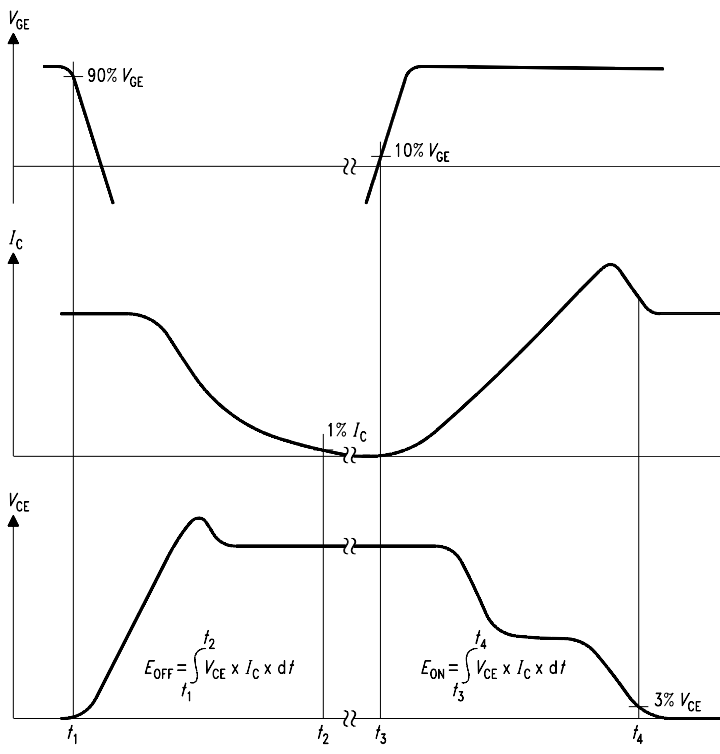
**Figure A. Definition of switching times**



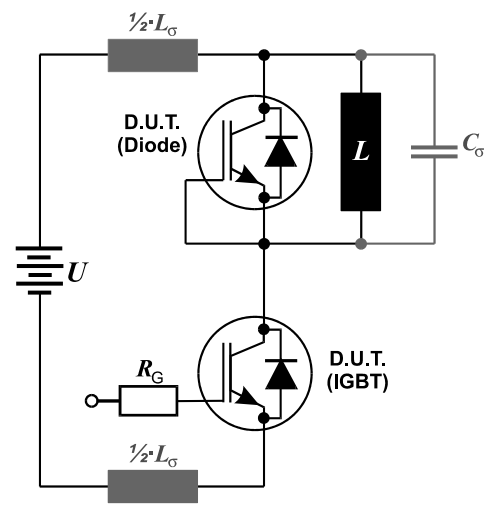
**Figure C. Definition of diodes switching characteristics**



**Figure D. Thermal equivalent circuit**



**Figure B. Definition of switching losses**



**Figure E. Dynamic test circuit**

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For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office ([www.infineon.com](http://www.infineon.com)).

### **Warnings**

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office. Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

## Данный компонент на территории Российской Федерации

### Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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